

Electroless plating equipment for wafer to make UBM



TORYZA EL SYSTEM

- ▶ Electroless plating equipment for 12 inch wafers
- ▶ Maximum treatment capacity, 50 pieces per batch
- ▶ High thickness uniformity in same wafer piece

Process for Al electrodes

Cleaning/Etching
TORYZA ALC W

Conditioning
TORYZA CD W

Desmutting
TORYZA DS W

1st zincate
TORYZA AZ W

Zincate stripping
TORYZA DS W

2nd zincate
TORYZA ZN W

Electroless Ni plating
TORYZA NCR HRC

Electroless Pd plating
(TORYZA PD LP)

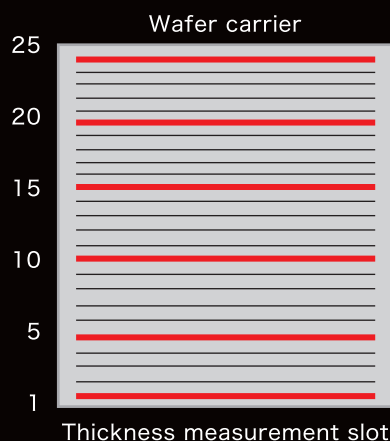
Electroless Au plating
TORYZA FG SR



Automatic open/close lid

- ▶ Applicable to 6,8,12 inch wafer
- ▶ 25 pieces, full carrier, 2 lines
- ▶ Conform to ISO 14644-1, Class 6 (Class 1000)
- ▶ Equipped with automatic recording system for production management and production monitoring

**12 inch wafer,
Maximum treatment capacity,
50 pieces per batch**



Thickness evaluation in a same 12-inch wafer after electroless Ni plating

**High thickness uniformity in same wafer piece
(CV ratio:2.0%)**

